

# **General Description**

The WSD50P10ADN56 is the highest performance trench P-ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSD50P10ADN56 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

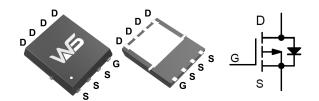
# **Product Summery**

BVDSS	RDSON	ID
-100V	62mΩ	-40A

# **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

# DFN5X6\_8L Pin Configuration



### **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-100	V
$V_{GS}$	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup>	-40	Α
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup> -27		А
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup> -110		А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	157	mJ
I <sub>AS</sub>	Avalanche Current	-18.9	А
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation⁴	104	W
T <sub>STG</sub>	Storage Temperature Range -55 to 150		$^{\circ}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^{\circ}$

### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>		62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>		1.2	°C/W



# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-100			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =-1mA		-0.021		V/℃
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-20A		62	81	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	-V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.2		-2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	VGS-VDS, ID250UA		4.08		mV/℃
la co	Drain-Source Leakage Current	$V_{DS}$ =-48V , $V_{GS}$ =0V , $T_J$ =25 $^{\circ}$ C			1	uA
I <sub>DSS</sub>	Drain-Source Leakage Guirent	$V_{DS}$ =-48V , $V_{GS}$ =0V , $T_J$ =55 $^{\circ}$ C			5	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}$ =0V			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =-10V , I <sub>D</sub> =-10A		24		S
$Q_{g}$	Total Gate Charge (-4.5V)			75		
$Q_gs$	Gate-Source Charge	V <sub>DS</sub> =-50V , V <sub>GS</sub> =-10V , I <sub>D</sub> =-18A		9		nC
$Q_gd$	Gate-Drain Charge			18		
T <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD}$ =-30V , $V_{GS}$ =-10V , $R_{G}$ =6 $\Omega$ , $I_{D}$ =-18A ,RG=30 $\Omega$ .		17		
Tr	Rise Time			6		ns
$T_{d(off)}$	Turn-Off Delay Time			75		115
T <sub>f</sub>	Fall Time			10		
Ciss	Input Capacitance	V <sub>DS</sub> =-30V , V <sub>GS</sub> =0V , f=1MHz		2590		
C <sub>oss</sub>	Output Capacitance			320		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			45		

# **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =-25V , L=0.5mH , I <sub>AS</sub> =-10A	100			mJ

### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			-40	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25℃			-1.2	V

#### Note:

A: The value of Reja is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with Ta=25°C. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

C: The current rating is based on the t≤ 10s junction to ambient thermal resistance rating.

D: Pulse Test: Pulse Wide≤ 300µs, Duty Cycle≤ 2%.



### **Typical Characteristics**

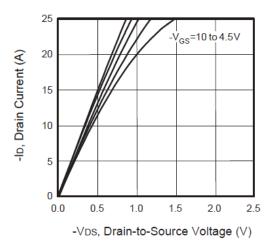


Figure 1. Output Characteristics

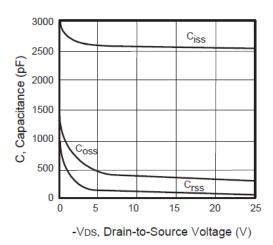


Figure 3. Capacitance

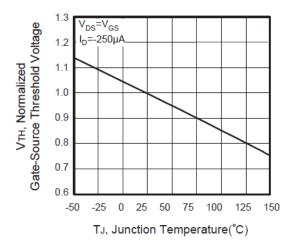


Figure 5. Gate Threshold Variation with Temperature

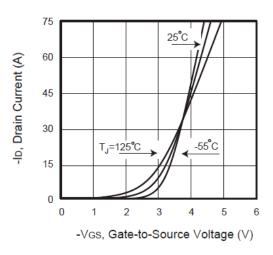


Figure 2. Transfer Characteristics

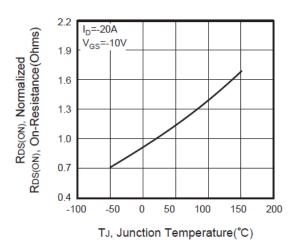


Figure 4. On-Resistance Variation with Temperature

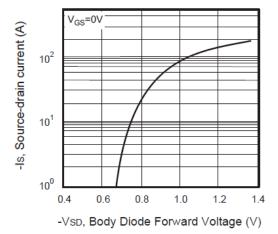


Figure 6. Body Diode Forward Voltage Variation with Source Current



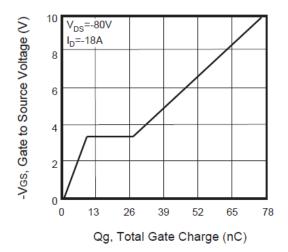


Figure 7. Gate Charge

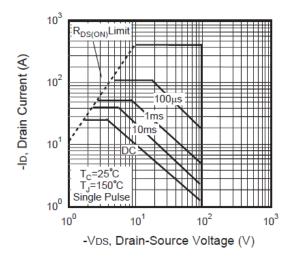


Figure 8. Maximum Safe Operating Area

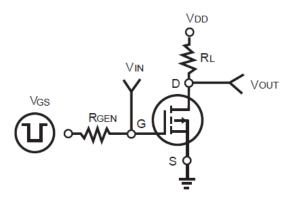


Figure 9. Switching Test Circuit

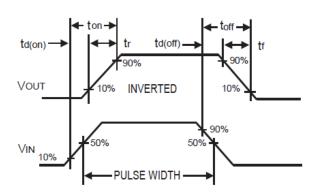


Figure 10. Switching Waveforms

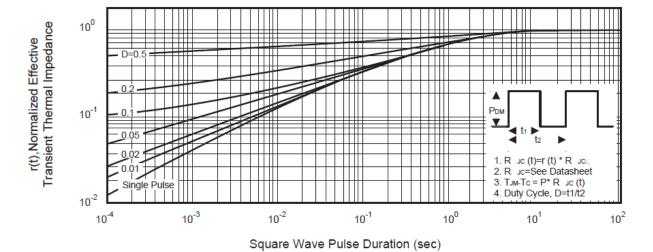


Figure 11. Normalized Thermal Transient Impedance Curve



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